

ABSTRACT OF THE DISCLOSURE

The present invention provides a thin film circuit board used as a milli-wave or micro-wave module, in which a patterned insulating film having a sufficient thickness can be stably formed. Such an insulating film is produced by the step of forming a conductor film in a predetermined pattern on a cleaned substrate and forming an insulating film on the substrate to cover the conductor film, the step of patterning the insulating film, the step of forming a second insulating film, and the step of patterning the insulating film. In this way, the insulating film forming step and the patterning step are repeated a required number of times.

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